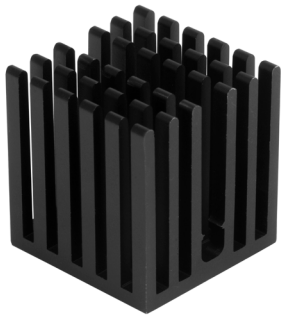
CUI DEVICES

MODEL: HSB23-232325 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- top mount
- aluminum alloy



RoHS

MODEL

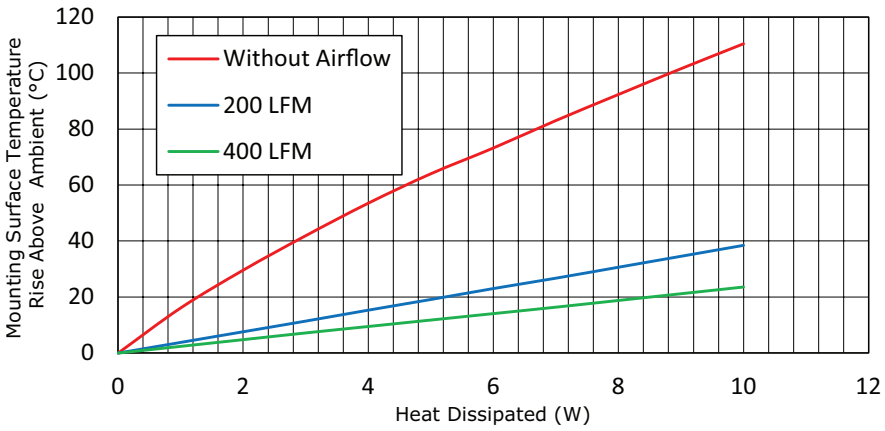
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSB23-232325	12.23	16.1	3.8	2.4	6.13

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	16.1	3.8	2.4
2	29.6	7.6	4.8
3	41.9	11.4	7.2
4	53.5	15.3	9.5
5	64.0	19.1	11.8
6	73.2	23.0	14.1
7	83.0	26.7	16.4
8	92.3	30.6	18.8
9	101.5	34.5	21.2
10	110.4	38.4	23.6

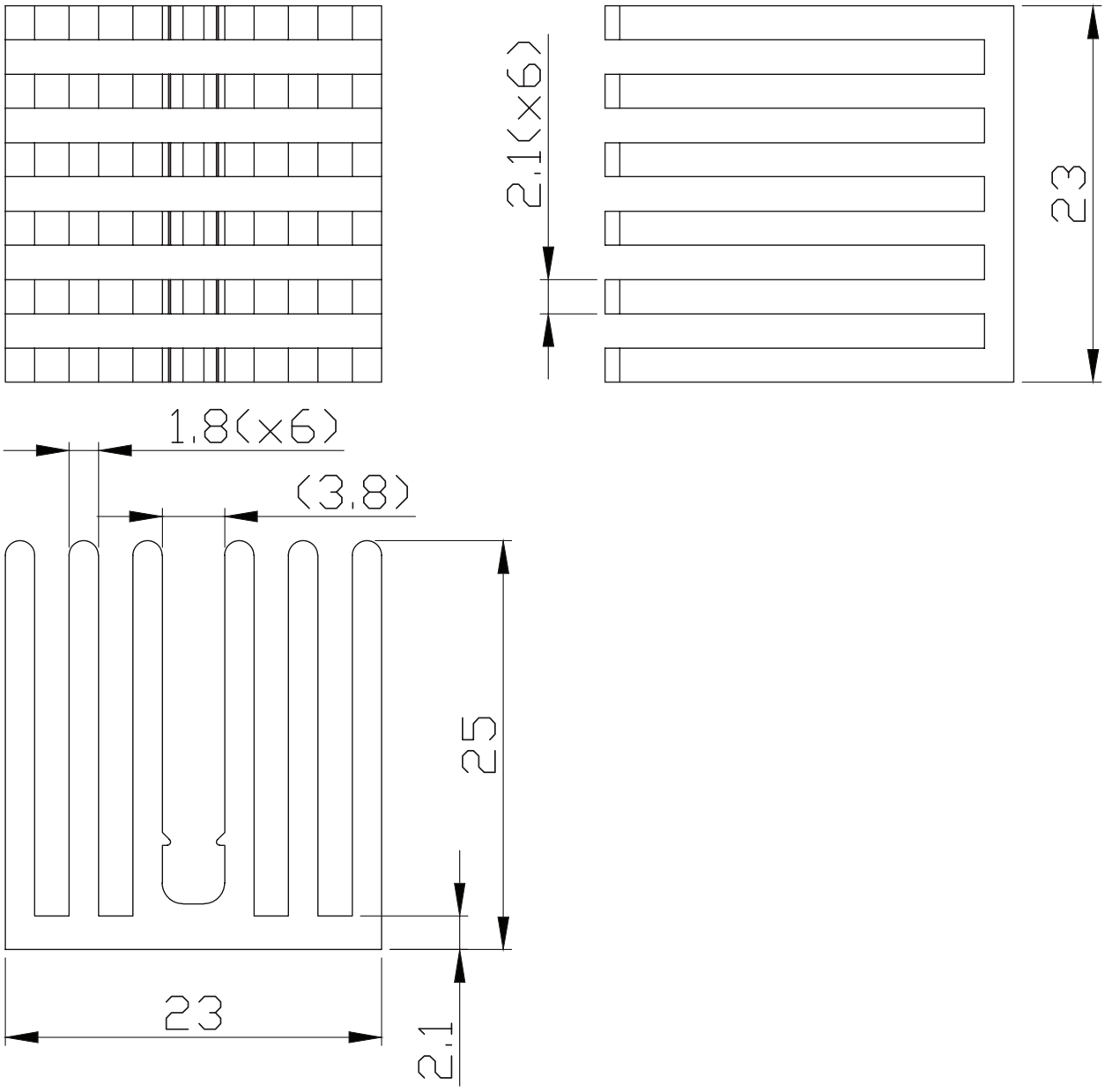
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	13.1 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/22/2022

The revision history provided is for informational purposes only and is believed to be accurate.